

Product Data Sheet

LF-4300 Lead-Free Water Washable No-Clean Solder Paste

Product Description

- Synthetic materials
- Can reflow high temperature alloys up to 300°C
- Complies with RoHS directive 2002/95/EC
- Excellent wetting compatibility with most board finishes
- Low voiding and mid-chip beading
- Residue can be left on or removed using water

Alloys

AMTECH manufactures a low-oxide, spherical and uniformly sized powder. LF-4300 is available in the following alloys: Sn96.5/Ag3.0/Cu.5, Sn96.5/Ag3.5, Sn99.3/Cu.7, Sn95/Sb5 and Sn95/Ag5 alloys.

Powder Distribution

Micron Size	Type	Pitch Requirements
75 - 45	Type-2	24mil & above
45 - 25	Type-3	16mil to 24 mil
38 - 20	Type-4	12mil to 16mil
25 - 15	Type-5	<12mil
15 - 5	Type-6	<8mil

Available Packaging

The following packaging options are available for stencil printing and dispensing applications: 250g and 500g jars; 250g and 700g cartridges; 750g ProFlow[®] cassettes; 35g and 100g syringes; 2,500g FreshMix[®] Kits.

Stencil Life

>8 hrs. @ 30–45% RH & 22–25°C
~4 hrs. @ 45–70% RH & 22–25°C

Viscosity

Printing applications: 600 to 900Kcps +/-10%
Dispensing applications: 400Kcps +/-10%
Tested according to IPC-TM-650

Tack Value

Typical tackiness: 37g force

Printing

The print definition of LF-4300 is ideal for fine pitch applications. The stencil life of this water-soluble product virtually eliminates waste of solder paste. Consult the powder distribution chart to determine your mesh size requirements.

Printer Operation

The following are general guidelines for stencil printer optimization with LF-4300. Some adjustments may be necessary based on your process requirements.

Print Speed: 25–100mm/sec

Squeegee Pressure: 0.2–0.7kg/inch of blade

Under Stencil Wipe: Once every 10–25 prints or as necessary

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using water at 60°C or 99% isopropyl alcohol (IPA). Post-reflow cleaning using water at 40–60°C with 30–50 PSI pressure.

Storage and Handling Procedures

Refrigerated storage at 42–47°F will prolong the solder paste shelf life to no less than 6 months. Syringes & cartridges should be stored vertically with the dispensing tip down. Solder paste should be allowed to reach ambient temperature naturally, prior to use (about 6–8 hours). NEVER FREEZE SOLDER PASTE.

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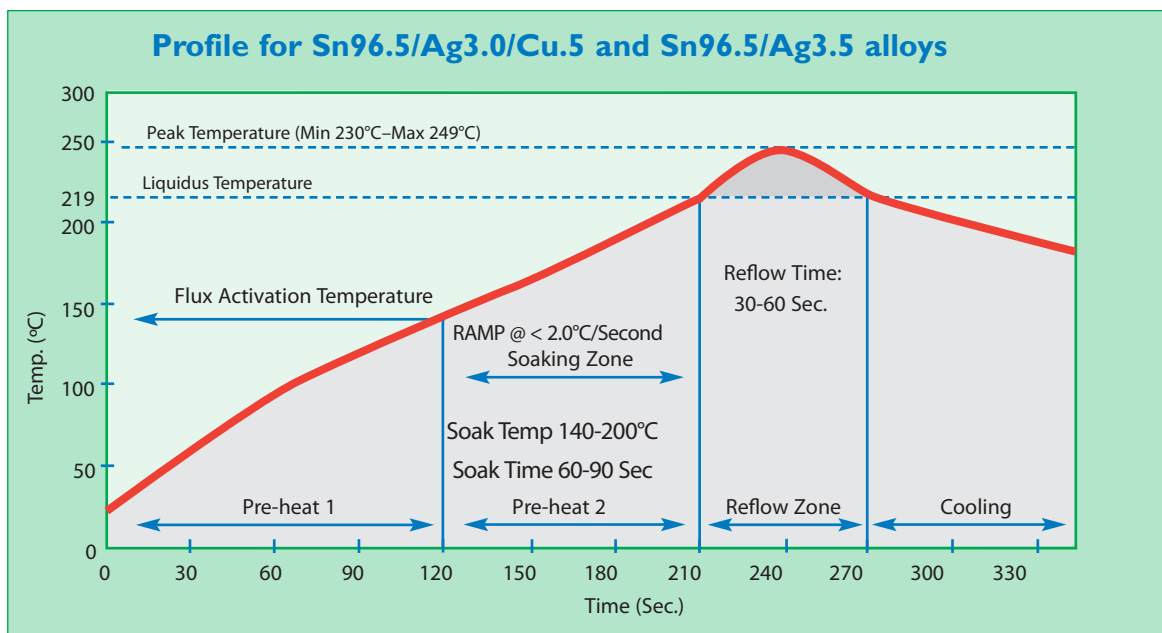
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J-STD-004 (IPC-TM-650) Test Results

Test	Standard	Values	Results
Flux Designator	IPC-TM-650 2.3.35	NA	RELO

Recommended Profile:

This profile was designed to serve as a starting point for process optimization using LF-4300. A cool down rate of (-) 2–4°C/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components.



The information contained herein is based on technical data that we believe to be reliable and is intended for use by persons having technical skill, at their own risk. Users of our products should make their own tests to determine the suitability of each product for their particular process. AMTECH will assume no liability for results obtained or damages incurred through the application of the data presented.

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